Quik-Pak Exhibits Open-Molded Plastic Packages, Air Cavity QFNs at International Microwave Symposium

IC Microelectronics Packaging/Assembly Services Provider in Booth 2229 Offers OmPP Packages, Air Cavity QFNs, with Superior Wire Bondability and RoHS/REACH-Compliant Molding Compounds and Assembly Services Designed to Accelerate Time to Market

San Diego, CA – May 23, 2016 – PRNewswire/iReach – Quik-Pak will showcase its Open-molded Plastic Packages (OmPP) for microwave and RF applications in Booth 2229 at the International Microwave Symposium (IMS), May 22-27 in San Francisco, California. Both air cavity QFN (Quad Flat No-Lead) Package and the Over Molded QFN Packages are available in off-the-shelf and custom configurations for prototype, mid volume and production volume requirements. Features of OmPP include:

- Gold plating for wire bondability and thermal regulation
- RoHS and REACH compliant green molding compound
- Short, highly conductive interconnects
- JEDEC outlines with matching ceramic, plastic and glass lids

Quik-Pak also offers complete assembly services to help accelerate time to market, including flip chip and wire bonding (Au, Al and Cu from 0.6-20 mil diameters) wafer thinning, dicing, and pick and place.

“While there are firms promising fast turns, few have the technical expertise, production resources and years of industry experience to provide the high level of quality that we do – even if you need your devices in eight hours,” said Quik-Pak Director of Sales and Marketing Casey Krawiec.

The International Microwave Symposium will host more than 8,500 attendees from around the world. In addition to the exhibition, this six-day event offers 75 technical sessions, workshops and panel sessions for designers, researchers, developers and academics in the microwave/RF industry.

About Quik-Pak

Quik-Pak’s IC packaging solutions for complex RF/MW devices include air cavity plastic QFN packages, over-molded plastic QFN/DFN packages, custom transfer molded packaging, and custom assembly for ceramic, laminate, COF and COB. Quik-Pak also offers assembly services from prototype design validation to full production, as well as wafer preparation services including dicing, backgrinding and pick and place. The company’s 15,000 square foot facility includes fully automated equipment for high throughput and maximum yield. Quik-Pak is a division of Promex Industries. More information about Quik-Pak is available at www.icproto.com, or by calling 858-674-4676.

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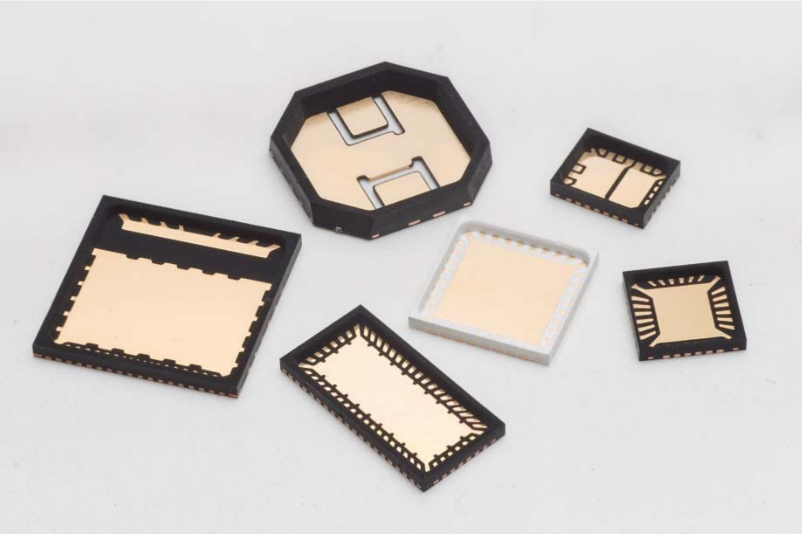

Custom Air Cavity QFNs